

DATA SHEET

An ON Semiconductor Company



N-Channel Silicon MOSFET **General-Purpose Switching Device Applications**

Features

- Low ON-resistance
- · Best suited for LiB charging and discharging switch
- Common-drain type
- 2.5V drive
- Halogen free compliance
- · Protection diode in

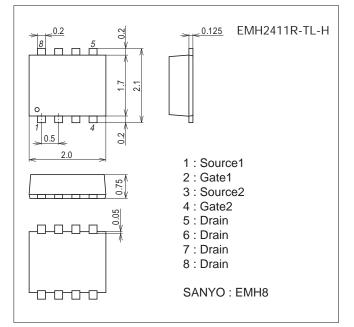
Specifications

Absolute Maximum Ratings at Ta=25°C

3				
Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		30	V
Gate-to-Source Voltage	VGSS		±12	V
Drain Current (DC)	ID		5	А
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	60	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm ² x0.8mm) 1unit	1.3	W
Total Dissipation	PT	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.4	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Package Dimensions

unit : mm (typ) 7045-006

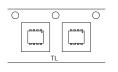


Product & Package Information : EMH8

- Package
- JEITA, JEDEC
- : -• Minimum Packing Quantity : 3,000 pcs./reel

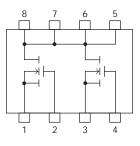
Packing Type : TL

Marking



LL LOT No.

Electrical Connection

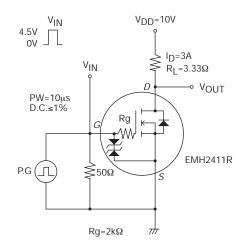


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Electrical Characteristics at Ta=25°C

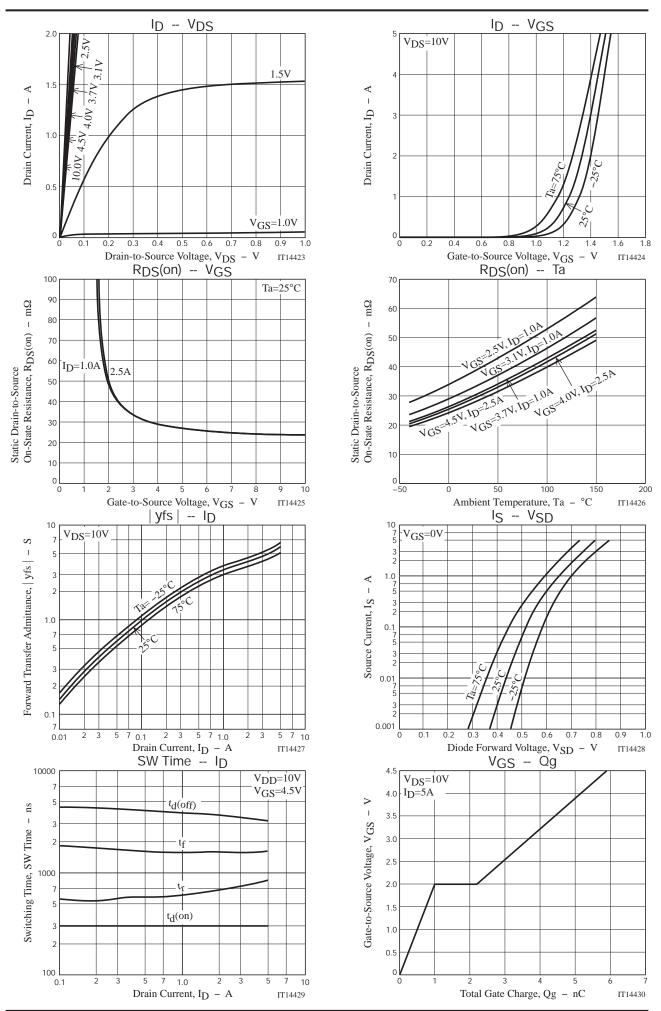
Parameter	Cumhal			Ratings			
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	30			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±8V, V _{DS} =0V			±10	μΑ	
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	0.5		1.3	V	
Forward Transfer Admittance	yfs	VDS=10V, ID=3A	3	5		S	
Static Drain-to-Source On-State Resistance	R _{DS} (on)1	ID=2.5A, VGS=4.5V	19.5	28	36.5	mΩ	
	R _{DS} (on)2	ID=2.5A, VGS=4V	20	29	38	mΩ	
	R _{DS} (on)3	ID=1A, VGS=3.7V	21	30	39	mΩ	
	RDS(on)4	ID=1A, VGS=3.1V	21	33	46.5	mΩ	
	RDS(on)5	ID=1A, VGS=2.5V	22.5	38	54	mΩ	
Turn-ON Delay Time	t _d (on)			300		ns	
Rise Time	tr			840		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit.		3200		ns	
Fall Time	tf			1650		ns	
Total Gate Charge	Qg			5.9		nC	
Gate-to-Source Charge	Qgs	V _{DS} =10V, V _{GS} =4.5V, I _D =5A		1		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		1.2		nC	
Diode Forward Voltage	VSD	IS=5A, VGS=0V		0.8	1.2	V	

Switching Time Test Circuit

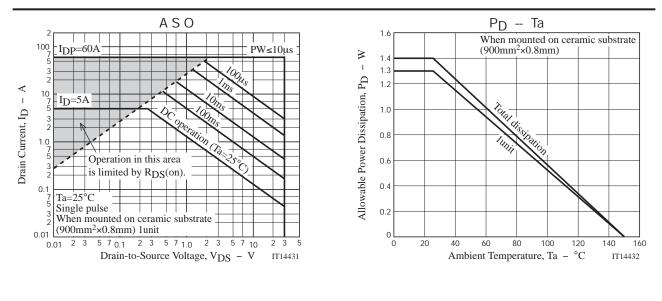


Ordering Information

Device	Device Package		memo		
EMH2411R-TL-H	EMH8	3,000pcs./reel	Pb Free and Halogen Free		



No. A1421-3/7



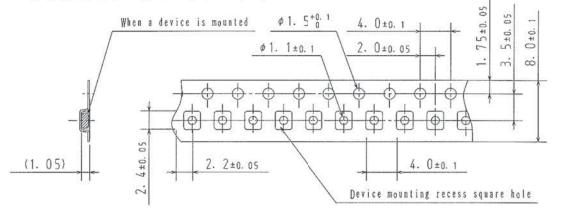
Embossed Taping Specification EMH2411R-TL-H

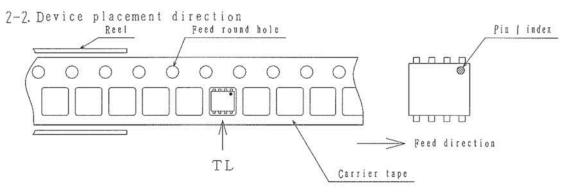
1. Packing Format

Package Name Carrier Tape Type		Maximum Number of devices contained (pcs)			Packing format				
		Reel	[nner box	Quter box	Inner	BOX	(C-1)	Outer BOX (A-7)	
EMH8	MCP4	3, 000	15, 000	90,000	5 reels co Dimension			6 inner boxes contained 1) Dimensions:mm (external)	
					183×			4 4 0 × 1 9 5 × 2 1 0	
Packing me	thod_		Reel		<u>nner box</u> nit:mm)	label	It i The	er box label s a label at the time of factory shipmen form of a label may change in physical ribution process.	
· ·			-	6	59	*		108	
	Type							TYPE CODE +000000000000000000000000000000000000	
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Y			NOTE	3 (1)	~			SPECIAL ####################################	
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				Label	s. I a	EITA	Phase		
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2. Taping configuration

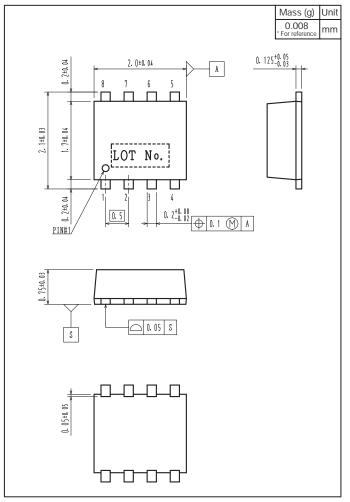
2-1. Carrier tape size (unit:mm)



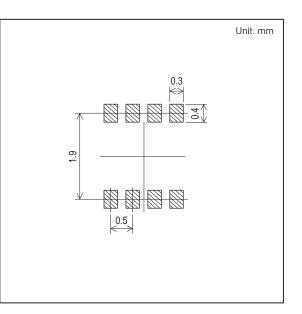


Those with pin 1 index on the feed hole side TL

Outline Drawing EMH2411R-TL-H



Land Pattern Example



Note on usage : Since the EMH2411R is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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